

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S):

Card et al.

**SERIAL NO.:** 

10/656,607

**GROUP NO.:** 

Not yet assigned

FILING DATE:

September 5, 2003

**EXAMINER:** 

Not yet assigned

TITLE:

Intelligent Control for Process Optimization and Parts Maintenance

### CERTIFICATE OF FIRST CLASS MAILING UNDER 37 C.F.R. 1.8

I hereby certify that this correspondence, and any document(s) referred to as enclosed herein, is/are being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 30 day of September, 2003.

Susan Boucher

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Submitted herewith is/are:

Transmittal Form (1 page); Information Disclosure Statement (3 pages); PTO Form 1449 (2 pages); copies of cited references (A-A5, B1-B2, C1-C13); and a return-receipt postcard.

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n 3 2003 E		Application Ser	ial Number	10/6	56,607			
TRADEMARKS	Filing Date		September 5, 2003					
TRAUEMA		First Named Inv	ventor	Card	Card			
TRANSMITTA	T	Group Art Unit		Not	Not yet assigned			
	L	Examiner Name	<b>;</b>	Not	Not yet assigned			
FORM		Attorney Docke	et No.	IBX-008				
		Patent No.		Not	Not applicable			
		Issue Date		Not	applicable			
	E	NCLOSURES (chec	k all that apply)					
☐ Fee Transmittal Form		Copy of Notice to Parts of Application	File Missing		Notice of Appeal to Board of Patent Appeals and Interferer			
☐ Check Attached☐ Copy of Fee Transmittal Form		Formal Drawing(s	3)		Appeal Brief (in triplicate)			
Amendment/Response		Request For Cont Examination (RC)			Status Inquiry			
☐ Preliminary ☐ After Final		Transmittal		$\boxtimes$	Return Receipt Postcard			
Affidavits/declaration(s) Letter to Official Draftsperson		Power of Attorney (Revocation of Pr		⊠	Certificate of First Class Mailin under 37 C.F.R. 1.8			
including Drawings [Total Sheets]		Terminal Disclain	ner		Certificate of Facsimile Transmission under 37 C.F.R. 1			
Petition for Extension of Time		Executed Declaration of Attorney for Ut Patent Application	tility or Design		Additional Enclosure(s) (please identify below)			
		Small Entity State	ement					
Form PTO-1449 Copies of IDS Citations		CD(s) for large tal	ble or computer					
Certified Copy of Priority Document(s)		Amendment After	Allowance					
Sequence Listing submission Paper Copy/CD Computer Readable Copy Statement verifying identity of above		Request for Certificate of duplicate)	Ticate of  Correction (in					

Testa, Hurwitz & Thibeault, LLP

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Date: September <u>30</u>, 2003 Reg. No. 33,497 Tel. No.: (617) 310-8108

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Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicants hereby make of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. Copies of the patents and publications are enclosed.

### **REMARKS**

In accordance with the provisions of 37 C.F.R. 1.97, this statement is being filed (CHECK ONE):

(1)	within three (3) months of the <b>filing date</b> of a national application other than a continued prosecution application under 37 C.F.R. 1.53(d), or within three (3) months of the <b>date of entry of the national stage</b> as set forth in 37 C.F.R. 1.491 in an international application, or before the mailing of the <b>first Office action</b> on the merits, or before the mailing of a <b>first Office action</b> after the filing of a request for continued examination under 37 C.F.R. 1.114; or
(2)	after the period defined in (1) but before the mailing date of a final action or a notice of allowance under 37 C.F.R. 1.311, and
	the requisite Statement is below, OR
	the requisite fee under 37 C.F.R. 1.17(p), namely \$180.00, is included herein, or

	. 10/656,6	ore Statement 07				
	(3)	after the mailing date of a final action or notice of allowance but before the payment of the issue fee, AND				
		the requisite Statement is below, AND				
		the requisite petition fee under 37 C.F.R. 1.17(p), namely \$180.00 is included herein.				
	•	fully requested that each of the patents and publications listed on the attached Form ther information contained herein, be made of record in this application.				
STATEMENT						
As	s required	under 37 C.F.R. 1.97(e), Applicant(s), through the undersigned, hereby state either that				
[check	the appr	opriate space only if either (2) or (3) is checked on the previous page <u>and</u> the				
Statem	ent is req	[uired]:				
		Each item of information contained in the Information Disclosure Statement was				
		first cited in any communication from a foreign patent office in a counterpart				
		foreign application not more than three months prior to the filing of the				
		Information Disclosure Statement; or				
		2. No item of information contained in the Information Disclosure Statement was				
		cited in a communication from a foreign patent office in a counterpart foreign				
		application, and, to the knowledge of the person signing this Statement after				
		making reasonable inquiry, no item of information contained in the Information				
		Disclosure Statement was known to any individual designated in 37 C.F.R.				
		1.56(c) more than three months prior to the filing of the Information				

In addition, Applicant wishes to inform the Examiner about the following co-pending patent applications, publications, issued patents, and Office Actions issued therein:

Disclosure Statement.

- U.S. Serial No. 10/243,963, filed on September 13, 2002, by Card et al. (IBX-001);
- U.S. Serial No. 10/244,154, filed on September 13, 2002, by Reitman et al. (IBX-002);
- U.S. Serial No. 10/645,209, filed on August 21, 2003, by Chan et al. (IBX-004); and
- U.S. Serial No. 10/621,532, filed on July 17, 2003, by Card et al. (IBX-005).

Information Disclosure Statement Serial No. 10/656,607 Page 3 of 3

Date: September 30, 2003

Reg. No. 33,497

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Respectfully submitted,

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FORM I	PTO - :	1449			ATTORN	EY DOC	KET NO.:	IBX-008	3	
INFORMATION DISCLOSURE STATEMENT					APPLICANT(S): Card et al.  SERIAL NO.: 10/656,607					
	<u></u>		U.S	. PATENT	DOCUM	ENTS		<b>-</b>		
EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME			CLASS	SUB CLASS		ING DATE IF PROPRIATE
	A1	5,467,883	11/21/95	Frye et al.			216	60	11/2	27/93
	A2	5,559,690	9/24/96	Keeler et	al.		364	164	9/16	5/94
	A3	5,654,903	8/5/97	Reitman e	t al.		364	551.01	11/7	1/95
	A4	5,740,033	4/14/98	Wassick e	t al.	-	364	149	10/1	13/92
	A5	6,268,226	7/31/01	Angell et	al.		438	16	6/30	)/99
			FORE	IGN PATE	NT DOCU	JMENTS	(			1
EXAM. INIT.		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	FILING DATE	ABSTR. ONLY	ACT	ENGLISH LANG (Y/N)
	Bi	WO 01/57605	8/9/01	wo	G05B	13/04	1/11/01	N		Y
	B2	DE196 37 917 A1	3/19/98	DE	G05B	13/04	9/17/96	Y		
		C	THER A	RT, JOURI	NAL ART	ICLES, F	ETC.			
EXAM. INIT.	ОТН	IER DOCUMENTS	3: (Includin	g Author, Ti	tle, Date, Re	levant Pag	ges, Place o	f Publicat	ion)	
	C1	Card et al., "Dyna (1997).	mic Neural (	Control for Pl	asma Etch P	rocess," <u>IE</u>	EE Transac	tions on N	leural ]	Networks,
	C2	Card et al., "Impacts of Maintenance Input on the Prediction Accuracy of an APC Controller," Presentation at AEC/APC Symposium XIV (September 9-11, 2002).								
	C3	Card et al., "Adva Maintenance," Pro	•	•				-	mizatio	on and Parts
	C4	Dillon et al., "Gue Networks, 8:4 (Ju		Everyday Apı	plications of	Neural Net	tworks," <u>IE</u>	EE Transa	ctions	on Neural
	C5	Hatzipantelis et al	•	•						

Condition Monitoring Applications," Artificial Neural Networks, 26-28, Conference Publication No. 409

(June 1995).

C6 Kim et al., "Intelligent Control of Via Formation by Photosensitive BCB for MCM-L/D Applications," IEEE Transactions on Semiconductor Manufacturing, 12:503 (1999).  C7 Konstantopoulos et al., "Controllers with Diagnostic Capabilities. A Neural Network Implementation. Journal of Intelligent and Robotic Systems," Department of Electrical Engineering, University of Notre Dame, IN 12: 197-228 (1995).  C8 Moyne, "AEC/APC Vision: A Research and Suppliers' Point of View," 3 <sup>rd</sup> Annual European AEC/APC Conference Proceedings (2002).  C9 Rietman et al., "A Study on ℜ™ → ℜ¹ Maps: Application to a 0.16-μm Via Etch Process Endpoint," IEEE (2000).  C10 Rietman et al., "A System Model for Feedback Control and Analysis of Yield: A Multistep Process Model of Effective Gate Length, Poly Line Width, and IV Parameters", IEEE (2001).  C11 Rietman, "Neural Networks in Plama Processing," Journal of Vacuum Science and Technology: Part B, IEEE Transactions on Semiconductor Manufacturing, 14:1 (2001).  C12 Smyth et. al., "Hidden Markov Models an Neural Networks for Fault detection in Dynamic Systems," California Institute of Technology (1993).  C13 Zhang et al, "Control of Spatial Uniformity in Microelectronics Manufacturing: An Integrated Approach," Proceedings of AEC/APC (2000).	EMARIE		
Journal of Intelligent and Robotic Systems," Department of Electrical Engineering, University of Notre Dame, IN 12: 197-228 (1995).  C8 Moyne, "AEC/APC Vision: A Research and Suppliers' Point of View," 3 <sup>rd</sup> Annual European AEC/APC Conference Proceedings (2002).  C9 Rietman et al., "A Study on ℜ" → ℜ¹ Maps: Application to a 0.16-μm Via Etch Process Endpoint," IEEE (2000).  C10 Rietman et al., "A System Model for Feedback Control and Analysis of Yield: A Multistep Process Model of Effective Gate Length, Poly Line Width, and IV Parameters", IEEE (2001).  C11 Rietman, "Neural Networks in Plama Processing," Journal of Vacuum Science and Technology: Part B. IEEE Transactions on Semiconductor Manufacturing, 14:1 (2001).  C12 Smyth et. al., "Hidden Markov Models an Neural Networks for Fault detection in Dynamic Systems," California Institute of Technology (1993).  C13 Zhang et al, "Control of Spatial Uniformity in Microelectronics Manufacturing: An Integrated Approach,"		C6	· · · · · · · · · · · · · · · · · · ·
Conference Proceedings (2002).  C9 Rietman et al., "A Study on ℜ" → ℜ¹ Maps: Application to a 0.16-μm Via Etch Process Endpoint,"  IEEE (2000).  C10 Rietman et al., "A System Model for Feedback Control and Analysis of Yield: A Multistep Process Model of Effective Gate Length, Poly Line Width, and IV Parameters", IEEE (2001).  C11 Rietman, "Neural Networks in Plama Processing," Journal of Vacuum Science and Technology: Part B, IEEE Transactions on Semiconductor Manufacturing, 14:1 (2001).  C12 Smyth et. al., "Hidden Markov Models an Neural Networks for Fault detection in Dynamic Systems," California Institute of Technology (1993).  C13 Zhang et al, "Control of Spatial Uniformity in Microelectronics Manufacturing: An Integrated Approach,"		C7	Journal of Intelligent and Robotic Systems," Department of Electrical Engineering, University of Notre
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California Institute of Technology (1993).  C13 Zhang et al, "Control of Spatial Uniformity in Microelectronics Manufacturing: An Integrated Approach,"		C11	
		C12	
		C13	

DATE CONSIDERED

**EXAMINER**